

**Thermal resistance**

Parameter	Symbol	Min.	Typ.	Max.	Unit
Thermal resistance, junction - ambient	R_{thJA}	-	-	150	C/W
Soldering temperature, wavesoldering for 10s	T_{sold}	-	-	265	C

Parameter	Symbol	Condition	Min.	Typ.	Max.	Unit
Drain-Source Breakdown Voltage	BV_{DSS}	$V_{GS} = 0V, I_D = 250\mu A$	60			V
Gate Threshold Voltage	$V_{GS(TH)}$	$V_{GS} = V_{DS}, I_D = 250\mu A$	1.5		2.5	V

Drain-Source Leakage Current I_D

Fig.1 Gate-Charge Characteristics

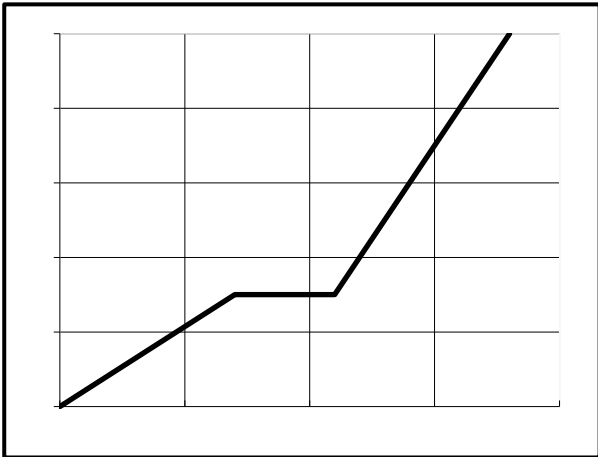


Fig.2 Capacitance Characteristics

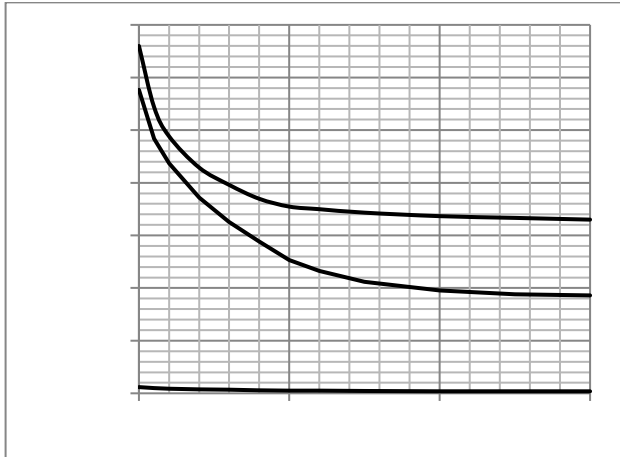


Fig.3 Power Dissipation

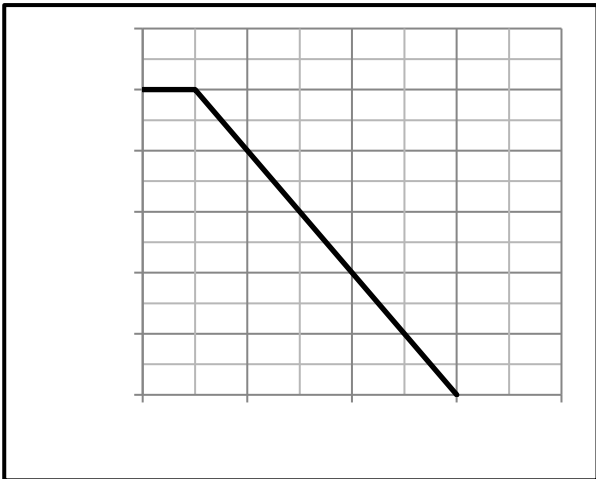


Fig.4 Typical output Characteristics

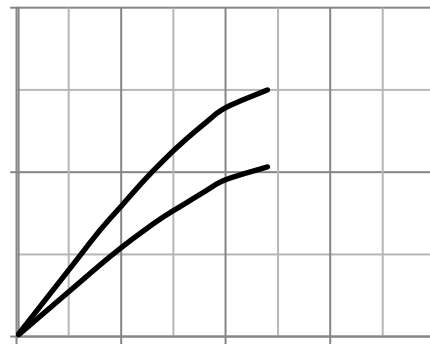


Fig.5 Threshold Voltage V.S Junction Temperature

Fig.6 Resistance V.S Drain Current

Fig.13 Switching Time Measurement Circuit

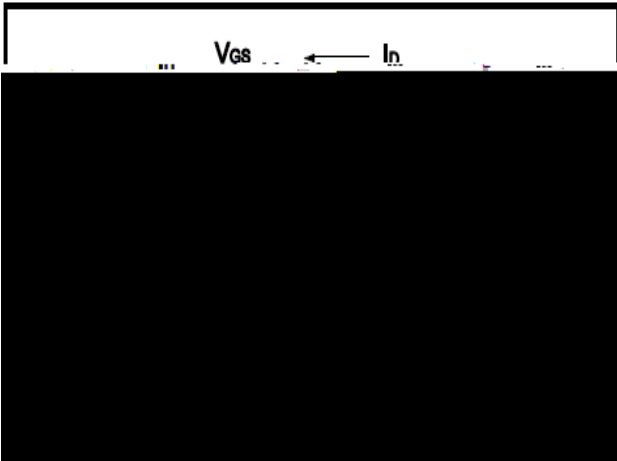


Fig.14 Gate Charge Waveform

